UBF nSMD Series (1206)

Electrical Characteristics

Part No	I_{hold} (A)	I_{trip} (A)	V_{max} (V)	I_{max} (A)	$P_{d\ type}$ (W)	Max. (A)	Time-to-trip (s)	R_{min} (Ω)	R_{1max} (Ω)
UBF nSMD 005	0.05	0.15	60	10	0.4	0.25	1.50	3.600	50.00
UBF nSMD 010	0.10	0.25	60	10	0.4	0.50	1.00	1.600	15.00
UBF nSMD 012	0.12	0.39	48	10	0.6	8.00	1.50	1.400	6.500
UBF nSMD 016	0.16	0.45	48	10	0.6	8.00	0.20	1.100	5.000
UBF nSMD 020	0.20	0.40	30	10	0.4	8.00	0.30	0.600	2.500
UBF nSMD 025	0.25	0.50	16	40	0.6	8.00	0.10	0.550	2.300
UBF nSMD 035	0.35	0.75	16	40	0.4	8.00	0.08	0.300	1.200
UBF nSMD 050	0.50	1.00	8	40	0.4	8.00	0.10	0.150	0.700
UBF nSMD 050/24	0.50	1.00	24	40	0.6	8.00	0.10	0.150	0.750
UBF nSMD 075	0.75	1.50	6	100	0.6	8.00	0.20	0.090	0.290
UBF nSMD 075/16	0.75	1.50	16	100	0.6	8.00	0.20	0.090	0.290
UBF nSMD 100	1.00	1.80	6	100	0.6	8.00	0.30	0.055	0.210
UBF nSMD 110	1.10	2.20	6	100	0.8	8.00	0.30	0.045	0.180
UBF nSMD 150	1.50	3.00	6	100	0.8	8.00	1.00	0.030	0.120
UBF nSMD 200	2.00	3.50	6	100	0.8	8.00	1.50	0.018	0.080

I_{hold}: Hold current is the maximum current that **BF Fuse** can pass through without interruption at 20°C unless otherwise specified.

I_{trip}: Trip current is the minimum current that will switch the device from low resistance state to high resistance state at 20°C unless specified.

V_{max}: The maximum voltage device can withstand without damage at rated current.

I_{max}: The maximum current device can withstand without damage at rated voltage.

P_d: The power dissipated from device when in the tripped state at 20°C unless otherwise specified.

R_{min}: The minimum resistance of device as received from the factory at 20°C unless otherwise specified.

R_{max}: The maximum resistance of device as received from the factory at 20°C unless otherwise specified.

R_{1max}: The maximum resistance of device when measured one hour post reflow at 20°C unless otherwise specified.

Max. Time-to-trip: The maximum time for device to trip at specified current ratings at 20°C unless otherwise specified.

Dimensions

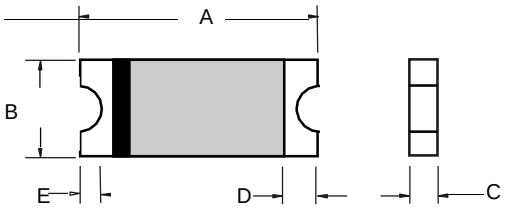
Part No	A		B		C		D		E	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
UBF hSMD	3.00	3.50	1.50	1.80	0.45	0.85	0.10	0.75	0.10	0.45

NOTE: All drawings are not in scale and layout may vary. All parts dimension is in millimeter unless otherwise pecified. Terminal material is Tin (Sn) plated Copper (Cu).

Packaging: 4000 pcs per reel

Agency Approval:

UL File Number	E 119550
c-UL File Number	E 119550
TUV File Number	Pending

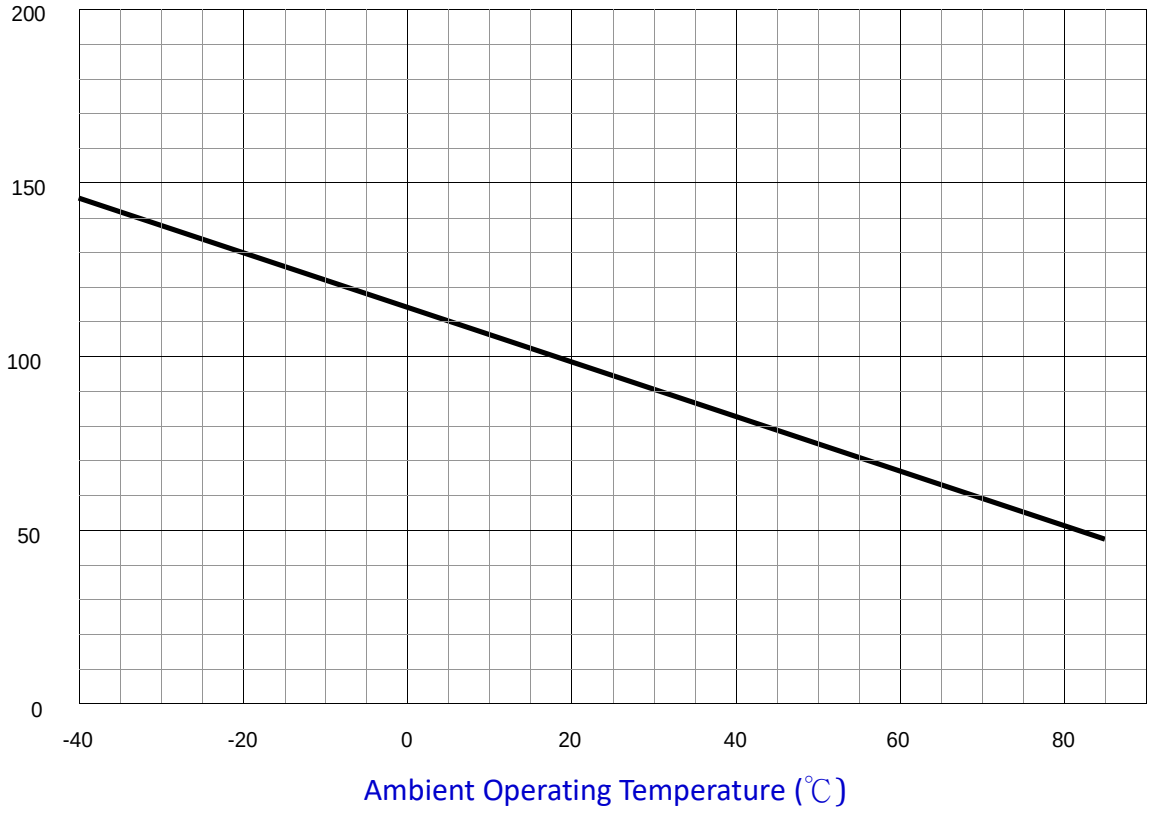


Top and Bottom Side View

UBF nSMD Series (1206)

Typical Thermal Derating Chart – I_{hold} (A)

Part No	-40	-20	0	20	40	60	85
UBFnSMD005	0.07	0.07	0.06	0.05	0.04	0.04	0.03
UBFnSMD010	0.15	0.14	0.12	0.10	0.09	0.07	0.05
UBFnSMD012	0.18	0.16	0.14	0.12	0.11	0.09	0.06
UBFnSMD016	0.24	0.22	0.19	0.16	0.14	0.11	0.08
UBFnSMD020	0.30	0.27	0.23	0.20	0.18	0.14	0.10
UBFnSMD025	0.37	0.34	0.29	0.25	0.22	0.18	0.13
UBFnSMD035	0.52	0.47	0.41	0.35	0.31	0.25	0.18
UBFnSMD050	0.74	0.68	0.59	0.50	0.44	0.36	0.26
UBFnSMD050/24	0.74	0.68	0.59	0.50	0.44	0.36	0.26
UBFnSMD075	1.09	1.01	0.88	0.75	0.66	0.53	0.39
UBFnSMD075/16	1.09	1.01	0.88	0.75	0.66	0.53	0.39
UBFnSMD100	1.45	1.35	1.17	1.00	0.88	0.71	0.52
UBFnSMD110	1.60	1.49	1.29	1.10	0.97	0.78	0.57
UBFnSMD150	2.18	2.03	1.76	1.50	1.32	1.07	0.78
UBFnSMD200	2.90	2.70	2.34	2.00	1.76	1.42	1.04

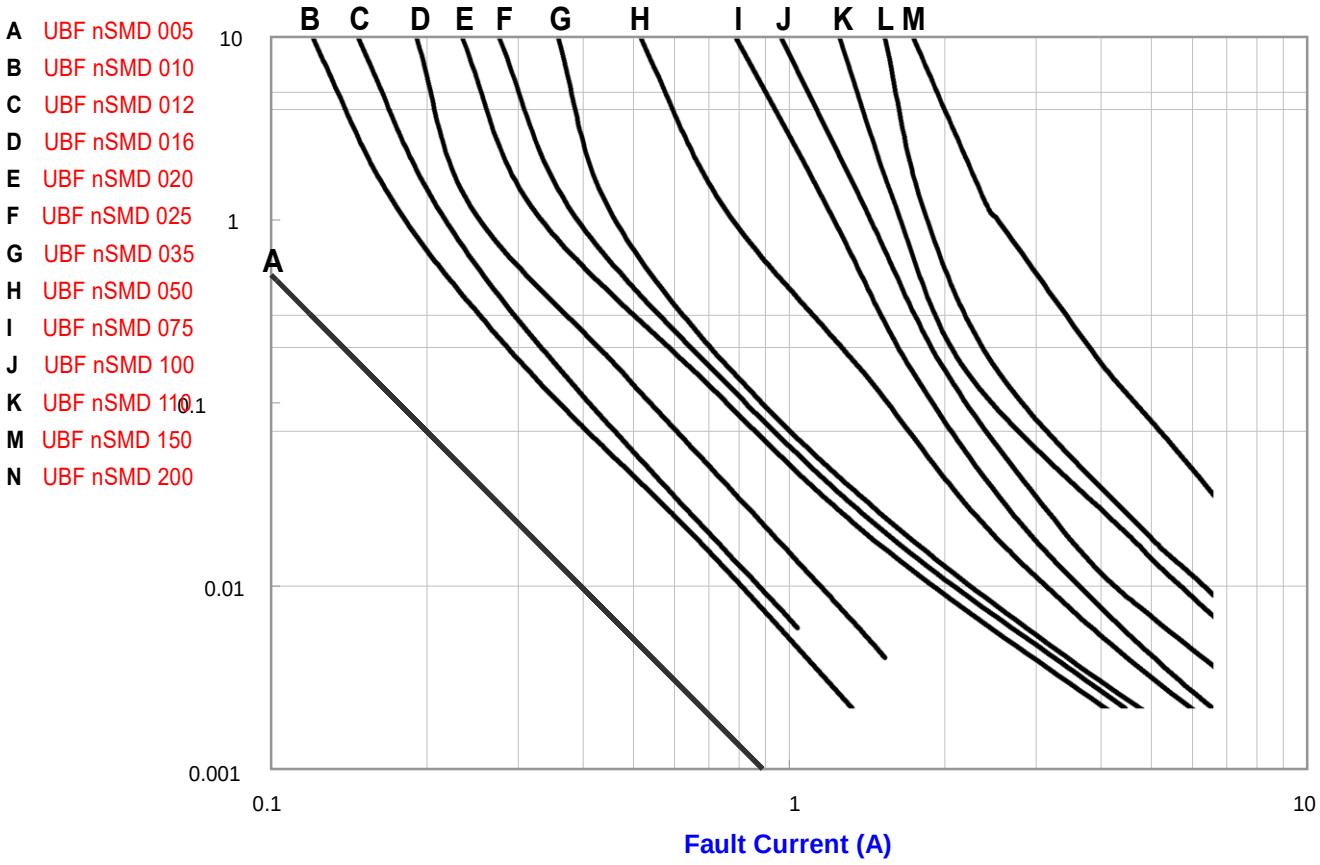


Environmental Characteristics

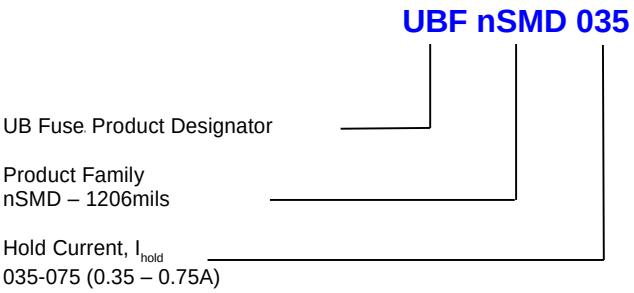
Test	Test Conditions	Resistance Change
Passive Aging	+85°C, 1000 hours	±10% typical resistance change
Humidity Aging	+85°C, 85% R.H., 7 days	±10% typical resistance change
Thermal Shock	+85°C to -40°C, 10 times	±10% typical resistance change
	MIL-STD-202, Method 107G	
Vibration	MIL-STD-883C, Condition A	No change
Solvent resistance	MIL-STD-202, Method 215	No change

UBF nSMD Series (1206)

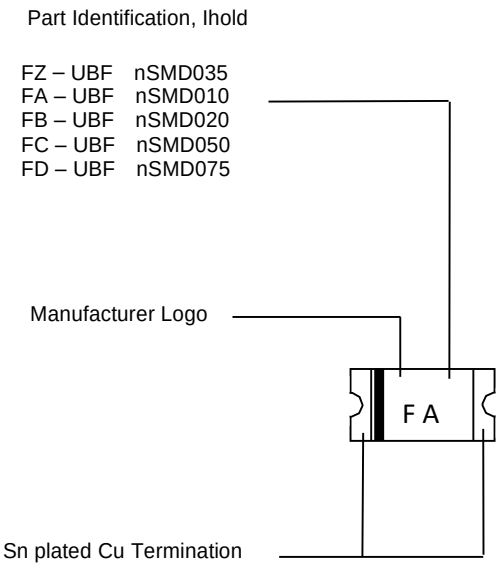
Typical Time To Trip Curve at 20°C



Ordering Information

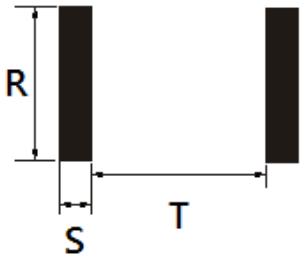


Part Marking



UBF nSMD Series (1206)

Recommended Reflow Profile & Pad Size

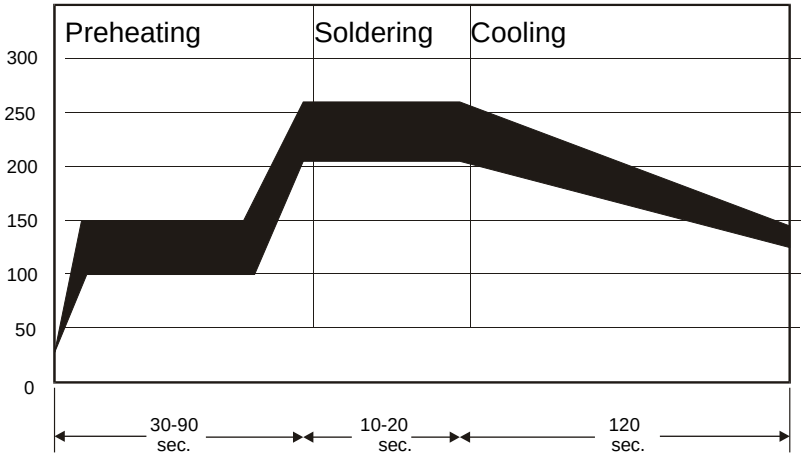


Recommended Pad Layout

Part No.	R	S	T
UBF nSMD005	1.60	1.00	2.00
UBF nSMD012	1.60	1.00	2.00
UBF nSMD016	1.60	1.00	2.00
UBF nSMD020	1.60	1.00	2.00
UBF nSMD025	1.60	1.00	2.00
UBF nSMD035	1.60	1.00	2.00
UBF nSMD050	1.60	1.00	2.00
UBF nSMD075	1.60	1.00	2.00
UBF nSMD100	1.60	1.00	2.00
UBF nSMD110	1.60	1.00	2.00
UBF nSMD150	1.60	1.00	2.00
UBF nSMD200	1.60	1.00	2.00

Reflow

- The recommended reflow profile is shown as the figure at right hand side.
- A maximum solder paste of thickness 0.25mm is recommended.
- Hot air, infra-red, vapor phase reflowing are recommended.

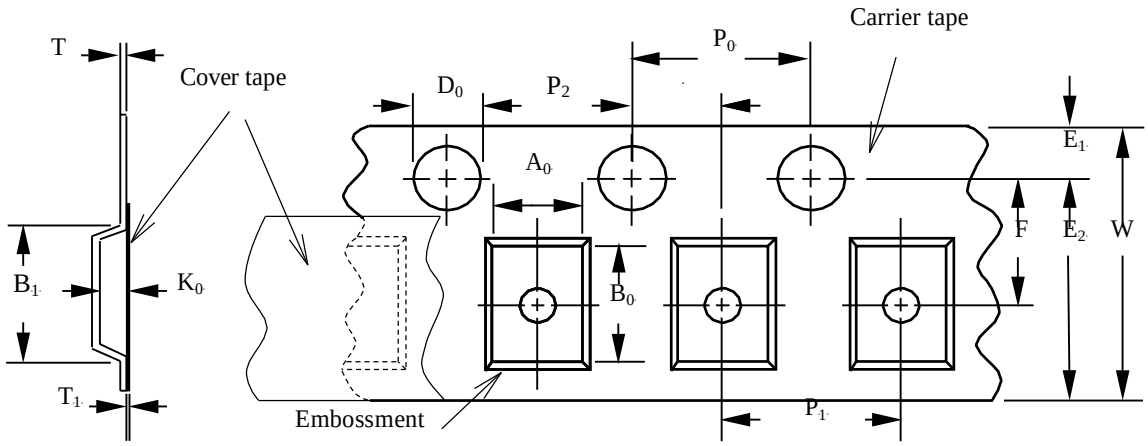


WARNING:

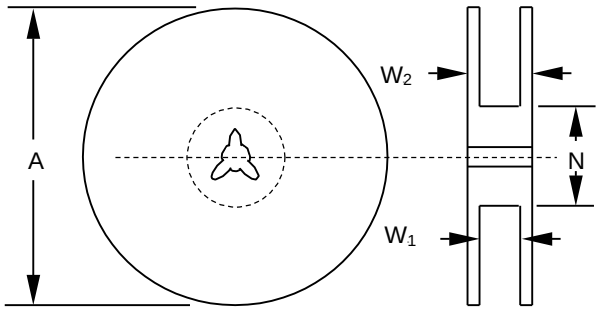
- Devices may not meet specifications if reflow temperatures exceed the recommended profile.
- Operation beyond maximum ratings or improper use may result in device damage and possible electrical arcing, flaming or explosion.
- The devices may not meet specified ratings if storage conditions exceeded 40°C and 70% relative humidity.
- The devices are intended to protect against occasional over-current or over-temperature fault conditions and should not be used when there are repeated fault conditions or prolonged trip events.
- The devices should not be placed under pressure or installed in spaces that would prevent thermal expansion, due to any prohibition of thermal expansion of the devices might result improper protection of fault conditions.
- UNIX TECH reserves the right to change any information or specification within this data book without notice.

UBF nSMD Series (1206)

Tape & Reel Packaging Specification per EIA481-1



Parameter as EIA481-1	Dimensions (mm)
W	8.00 ± 0.30
P_0	4.00 ± 0.10
P_1	4.00 ± 0.10
P_2	2.00 ± 0.05
A_0	1.88 ± 0.10
B_0	3.50 ± 0.10
B_1 max.	4.35
D_0	1.50 +0.10/-0.00
F	3.50 ± 0.05
E_1	1.75 ± 0.10
E_2 min.	6.25
T max.	0.6
T_1 max.	0.1
K_0	0.90 ± 0.10



Parameter as EIA481-1	Dimensions (mm)
A max.	185
N min.	50
W1	8.4 +1.5/-0.0
W2 max.	14.4